

# LM60 2.7V, SOT-23 or TO-92 Temperature Sensor

## 1 Features

- Industry-Standard Sensor Gain/Offset:
  - 6.25mV/°C, 424 mV at 0°C
- LM60B Temperature Accuracy:
  - ±2°C (Max) at 25°C
  - ±3°C (Max) over –25°C to +125°C (Legacy chip) and –40°C to +125°C (New chip)
- LM60C Temperature Accuracy:
  - ±3°C (Max) at 25°C
  - ±4°C (Max) over –40°C to +125°C
- Wide Supply Range: 2.7V to 10V
- Quiescent Current at 25°C: 110µA (Max/Legacy chip) and 70µA (Max/New chip)
- Available Package Options:
  - SOT-23 (3-pin)
  - TO-92 (3-pin, Straight Leads)
  - TO-92 (3-pin, Formed Leads)
- Nonlinearity: ±0.8°C (Maximum)
- DC Output Impedance: 120Ω/800Ω (typ/Max)
- Suitable for Remote Applications

## 2 Applications

- [Mobile phones, PC & notebooks](#)
- [Power supply modules](#)
- [Battery management](#)
- [Home and Multifunction printers](#)
- [HVAC and Solid state drive](#)
- [Appliances](#)

## 3 Description

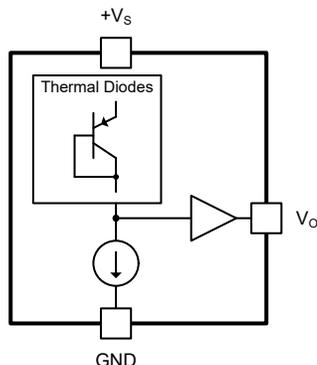
The LM60 device is a precision integrated-circuit temperature sensor that can sense a –40°C to +125°C temperature range while operating from a single 2.7V to 10V supply. The output voltage of the device is linearly proportional to Celsius (Centigrade) temperature (6.25mV/°C) and has a DC offset of 424mV. The offset allows reading negative temperatures without the need for a negative supply. The nominal output voltage of the device ranges from 174mV to 1205mV for a –40°C to +125°C temperature range. The device is calibrated to provide accuracies of ±2°C at room temperature and ±3°C over the full –25°C to +125°C (for Legacy chip) or –40°C to +125°C (for New chip) temperature range.

The linear output of the device, 424mV offset, and factory calibration simplify external circuitry required in a single supply environment where reading negative temperatures is required. Because the quiescent current of the device is less than 110µA (for Legacy chip) and 70µA (for New chip), self-heating is limited to a very low 0.1°C in still air in the SOT-23 package. Shutdown capability for the device is intrinsic because the inherent low power consumption allows the device to be powered directly from the output of many logic gates.

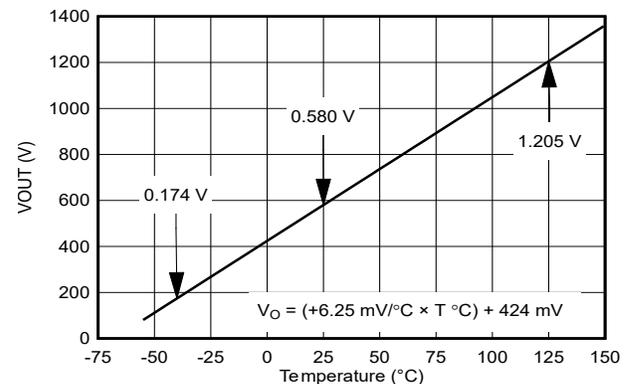
### Package Information

PART NUMBER	PACKAGE <sup>(1)</sup>	PACKAGE SIZE <sup>(2)</sup>
LM60	LP (TO-92, 3)	4.83mm × 7.37mm
	DBZ (SOT-23, 3)	2.37mm × 2.92mm

- (1) For all available packages, see the orderable addendum at the end of the data sheet.
- (2) The package size (length × width) is a nominal value and includes pins, where applicable.



Simplified Schematic



Full-Range Centigrade Temperature Sensor  
(–40°C to +125°C)



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## 4 Device Comparison

Table 4-1. Device Comparison

ORDER NUMBER	PACKAGE	ACCURACY OVER TEMPERATURE	SPECIFIED TEMPERATURE RANGE
LM60BIM3X/NOPB	SOT-23 (DBZ) 3-pin	$\pm 3^{\circ}\text{C}$	$-25^{\circ}\text{C} \leq T_A \leq +125^{\circ}\text{C}^{(1)}$ (Legacy chip)
LM60CIM3X/NOPB			$-40^{\circ}\text{C} \leq T_A \leq +125^{\circ}\text{C}$ (New chip)
LM60QIM3X/NOPB		$\pm 4^{\circ}\text{C}$	$-40^{\circ}\text{C} \leq T_A \leq +125^{\circ}\text{C}$
LM60BIZ/LFT3	TO-92 (LP) 3-pin Formed Leads	$\pm 3^{\circ}\text{C}$	$-25^{\circ}\text{C} \leq T_A \leq +125^{\circ}\text{C}^{(1)}$ (Legacy chip)
LM60BIZ/NOPB			$-40^{\circ}\text{C} \leq T_A \leq +125^{\circ}\text{C}$ (New chip)
LM60CIZ/NOPB	TO-92 (LP) 3-pin Straight Leads	$\pm 3^{\circ}\text{C}$	$-25^{\circ}\text{C} \leq T_A \leq +125^{\circ}\text{C}^{(1)}$ (Legacy chip)
LM60CIZ/NOPB			$-40^{\circ}\text{C} \leq T_A \leq +125^{\circ}\text{C}$ (New chip)
LM60CIZ/NOPB		$\pm 4^{\circ}\text{C}$	$-40^{\circ}\text{C} \leq T_A \leq +125^{\circ}\text{C}$

(1) LM60B (Legacy chip) operates down to  $-40^{\circ}\text{C}$  without damage but the accuracy is only verified from  $-25^{\circ}\text{C}$  to  $125^{\circ}\text{C}$ .

Table 4-2. Device Nomenclature

PRODUCT	OUT
LM60xlyyy/NOPB LM60xlyyy/LFT3	<p><b>x</b> indicates that the device has <b>B</b>, <b>C</b> or <b>Q</b> (grade-1 device in accordance with the AEC-Q100 standard) variant. These devices can ship with the legacy chip (CSO: GF6 or SHE) or the new chip (CSO: RFB) with different <i>date code</i>. The reel packaging label provides date code information to distinguish which chip is being used. Device performance for new and legacy chips is denoted throughout the document.</p> <p><b>yyy</b> indicates that the package type of the device which can be <b>M3X/NOPB</b> (SOT-23 3-pin) or <b>Z/LFT3</b> (TO-92 3-pin Formed Leads) or <b>Z/NOPB</b> (TO-92 3-pin Straight Leads).</p> <p>For more information on TO-92 package options please see: <a href="#">TO-92 Packing Options / Ordering Instructions</a></p>

## 5 Pin Configuration and Functions

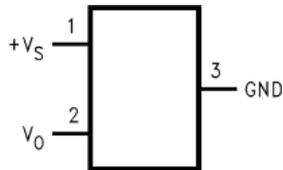


Figure 5-1. DBZ Package  
3-Pin SOT-23  
Top View

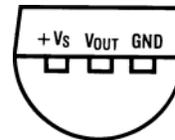


Figure 5-2. LP Package  
3-Pin TO-92  
(Formed Leads and Straight Leads)  
Bottom View

Table 5-1. Pin Functions

NAME	PIN		TYPE	DESCRIPTION
	SOT-23	TO-92		
GND	3	3	GND	Device ground, connected to power supply negative terminal
V <sub>OUT</sub>	2	2	O	Temperature sensor analog output
+V <sub>S</sub>	1	1	POWER	Positive power supply pin

## 6 Specifications

### 6.1 Absolute Maximum Ratings

Over operating free-air temperature range unless otherwise noted<sup>(1)</sup>

		MIN	MAX	UNIT
Supply voltage, +V <sub>S</sub>	LM60	-0.2	12	V
Output voltage, V <sub>O</sub>		-0.6	+V <sub>S</sub> + 0.6	V
Output current, I <sub>OUT</sub>			10	mA
Input current at any pin <sup>(2)</sup>			5	mA
Maximum junction temperature, T <sub>JMAX</sub>			125	°C
Storage temperature, T <sub>stg</sub>		-65	150	°C

- (1) Operation outside the *Absolute Maximum Ratings* may cause permanent device damage. *Absolute Maximum Ratings* do not imply functional operation of the device at these or any other conditions beyond those listed under *Recommended Operating Conditions*. If used outside the *Recommended Operating Conditions* but within the *Absolute Maximum Ratings*, the device may not be fully functional, and this may affect device reliability, functionality, performance, and shorten the device lifetime.
- (2) When the input voltage (V<sub>I</sub>) at any pin exceeds power supplies (V<sub>I</sub> < GND or V<sub>I</sub> > +V<sub>S</sub>), the current at that pin must be limited to 5mA.

### 6.2 ESD Ratings

			VALUE	UNIT
V <sub>(ESD)</sub> , Electrostatic discharge	LM60 (DBZ Package)	Human-body model (HBM), per ANSI/ESDA/JEDEC JS-001 <sup>(1)</sup>	±2500	V
		Charged-device model (CDM), per JEDEC specification JESD22-C101 <sup>(2)</sup>	±1000	
	LM60 (LP Package)	Human-body model (HBM), per ANSI/ESDA/JEDEC JS-001 <sup>(1)</sup>	±2500	
		Charged-device model (CDM), per JEDEC specification JESD22-C101 <sup>(2)</sup>	±1000	

- (1) JEDEC document JEP155 states that 500V HBM allows safe manufacturing with a standard ESD control process.
- (2) JEDEC document JEP157 states that 250V CDM allows safe manufacturing with a standard ESD control process.

### 6.3 Recommended Operating Conditions

Over operating free-air temperature range (unless otherwise noted)<sup>(1)</sup>

			MIN	MAX	UNIT	
+V <sub>S</sub>	Supply voltage	LM60	2.7	10	V	
T <sub>A</sub> , (T <sub>MIN</sub> ≤ T <sub>A</sub> ≤ T <sub>MAX</sub> )	Specified temperature	LM60B	Legacy chip	-25 <sup>(2)</sup>	125	°C
		LM60B	New chip	-40	125	°C
		LM60C		-40	125	°C

- (1) Soldering process must comply with National Semiconductor's Reflow Temperature Profile specifications. Refer to [www.national.com/packaging](http://www.national.com/packaging). Reflow temperature profiles are different for lead-free and non-lead-free packages.
- (2) LM60B (Legacy chip) operates down to -40°C without damage but the accuracy is only ensured from -25°C to 125°C.

### 6.4 Thermal Information

THERMAL METRIC <sup>(1)</sup>		LM60				UNIT
		DBZ (SOT-23) 3 PINS		LP (TO-92) 3 PINS		
		Legacy chip	New chip	Legacy chip	New chip	
R <sub>θJA</sub> <sup>(2)</sup>	Junction-to-ambient thermal resistance	266	240.6	162	135.9	°C/W
R <sub>θJC(top)</sub>	Junction-to-case (top) thermal resistance	135	144.5	85	109.1	°C/W
R <sub>θJB</sub>	Junction-to-board thermal resistance	59	72.3	-	108.9	°C/W
ψ <sub>JT</sub>	Junction-to-top characterization parameter	18	28.7	29	24.6	°C/W
ψ <sub>JB</sub>	Junction-to-board characterization parameter	58	71.7	142	108.9	°C/W

- (1) For more information about traditional and new thermal metrics, see the [Semiconductor and IC Package Thermal Metrics](#) application note.
- (2) The junction to ambient thermal resistance (R<sub>θJA</sub>) is specified without a heat sink in still air.

## 6.5 Electrical Characteristics

Unless otherwise noted, these specifications apply for  $+V_S = 3V$  (DC) and  $I_{LOAD} = 1\mu A$ . All limits  $T_A = T_J = 25^\circ C$  unless otherwise noted.

PARAMETER		TEST CONDITIONS		MIN <sup>(1)</sup>	TYP <sup>(2)</sup>	MAX <sup>(1)</sup>	UNIT
<b>SENSOR ACCURACY</b>							
$T_{ACY}$	Temperature accuracy <sup>(3)</sup>	LM60B <sup>(4)</sup>		-2		2	°C
			$T_A = T_J = T_{MIN}$ to $T_{MAX}$	-3		3	
		LM60C		-3		3	
			$T_A = T_J = T_{MIN}$ to $T_{MAX}$	-4		4	
<b>SENSOR OUTPUT</b>							
$V_{0^\circ C}$	Output voltage offset at 0°C				424		mV
$T_C$	Temperature coefficient (sensor gain)				6.25		mV/°C
		LM60B	$T_A = T_J = T_{MIN}$ to $T_{MAX}$	6.06		6.44	
		LM60C	$T_A = T_J = T_{MIN}$ to $T_{MAX}$	6		6.5	
$V_{ONL}$	Output Nonlinearity <sup>(5)</sup>	LM60B	$T_A = T_J = T_{MIN}$ to $T_{MAX}$	-0.6		0.6	°C
		LM60C	$T_A = T_J = T_{MIN}$ to $T_{MAX}$	-0.8		0.8	
$Z_{OUT}$	Output impedance					800	Ω
$T_{LTD}$	Long-term stability and drift <sup>(6)</sup>		$T_J = T_{MAX} = 125^\circ C$ for 1000 hours		±0.2		°C
<b>POWER SUPPLY</b>							
$I_{DD}$	Operating current	LM60, $2.7V \leq +V_S \leq 10V$	Legacy chip		82	110	μA
			New chip		52	70	
			$T_A = T_J = T_{MIN}$ to $T_{MAX}$			125	
			Legacy chip			90	
PSR	Line regulation <sup>(7)</sup>	LM60, $2.7V \leq +V_S \leq 3.3V$	$T_A = T_J = T_{MIN}$ to $T_{MAX}$	-2.3		2.3	mV
		LM60, $3V \leq +V_S \leq 10V$	$T_A = T_J = T_{MIN}$ to $T_{MAX}$	-0.3		0.3	mV/V
$\Delta I_{DD}$	Change of quiescent current	LM60, $2.7V \leq +V_S \leq 10V$	Legacy chip		±5		μA
			New chip		±6.5		
$I_{DD\_TEM P}$	Temperature coefficient of quiescent current				0.2		μA/°C

- (1) Limits are specified to TI's AOQL (Average Outgoing Quality Level).
- (2) Typicals are at  $T_J = T_A = 25^\circ C$  and represent most likely parametric norm.
- (3) Accuracy is defined as the error between the output voltage and  $6.25mV/^\circ C$  times the case temperature of the device plus 424mV, at specified conditions of voltage, current, and temperature (expressed in °C).
- (4) LM60B (Legacy chip) operates down to  $-40^\circ C$  without damage but the accuracy is only verified from  $-25^\circ C$  to  $125^\circ C$ . However, LM60B (New chip) specs are verified from  $-40^\circ C$  to  $125^\circ C$ .
- (5) Nonlinearity is defined as the deviation of the output-voltage-versus-temperature curve from the best-fit straight line, over the rated temperature rating of the device
- (6) For best long-term stability, any precision circuit provides the best results if the unit is aged at a warm temperature, temperature cycled for at least 46 hours before long-term life test begins for both temperatures. This is especially true when a small (surface-mount) part is wave soldered; allow time for stress relaxation to occur. The majority of the drift will occur in the first 1000 hours at elevated temperatures. The drift after 1000 hours will not continue at the first 1000 hour rate.
- (7) Regulation is measured at constant junction temperature, using pulse testing with a low duty cycle. Changes in output due to heating effects can be computed by multiplying the internal dissipation by the thermal resistance

## 6.6 Typical Characteristics

To generate these curves, the device is mounted to a printed-circuit board as shown in [Figure 8-9](#) or [Figure 8-10](#).

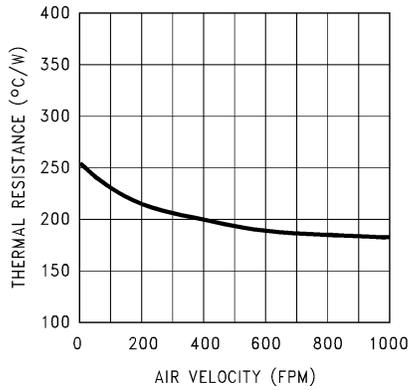


Figure 6-1. Thermal Resistance Junction to Air (Legacy chip)

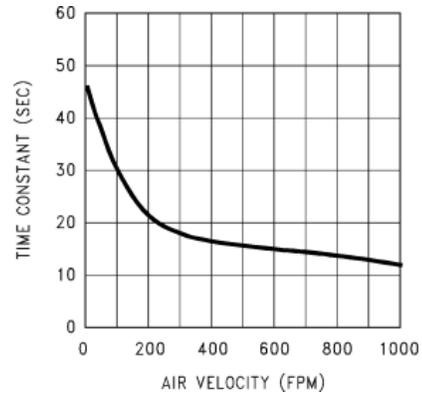


Figure 6-2. Thermal Time Constant (Legacy chip)

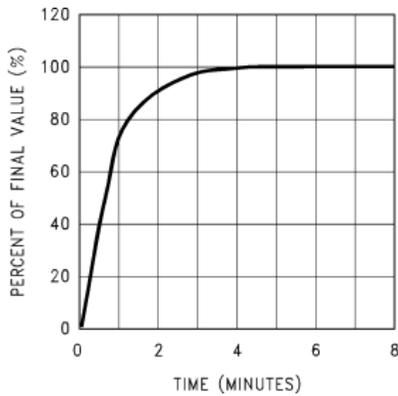


Figure 6-3. Thermal Response in Still Air With Heat Sink (Legacy chip)

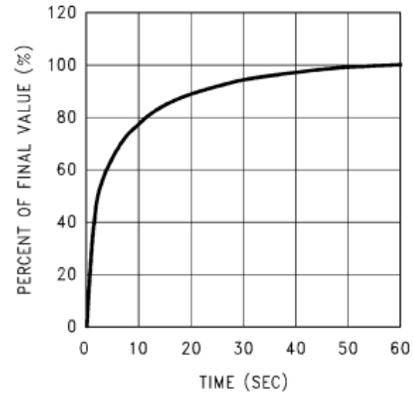


Figure 6-4. Thermal Response in Stirred Oil Bath With Heat Sink (Legacy chip)

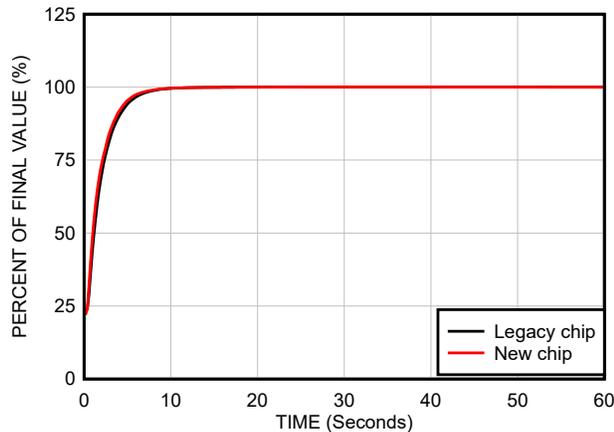


Figure 6-5. Thermal Response in Stirred Oil Bath With Heat Sink (0.5 inches x 0.5 inches PCB board)

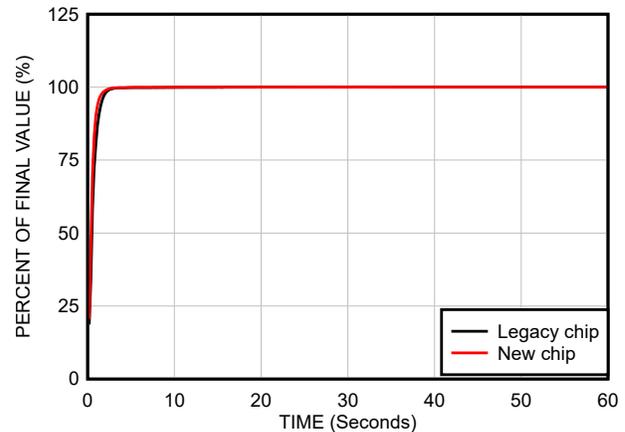
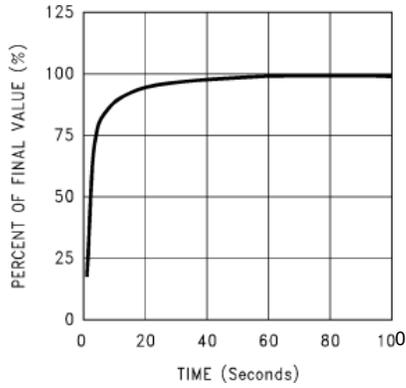


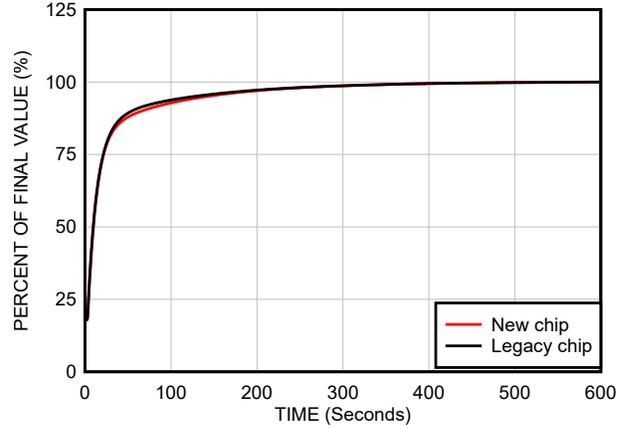
Figure 6-6. Thermal Response in Stirred Oil Bath Without Heat Sink

## 6.6 Typical Characteristics (continued)

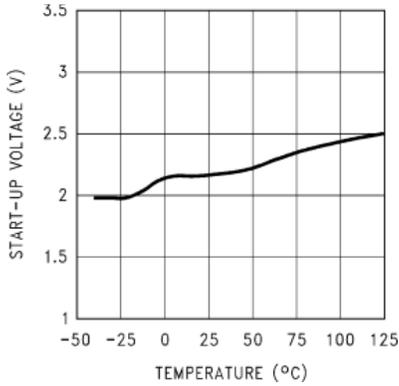
To generate these curves, the device is mounted to a printed-circuit board as shown in [Figure 8-9](#) or [Figure 8-10](#).



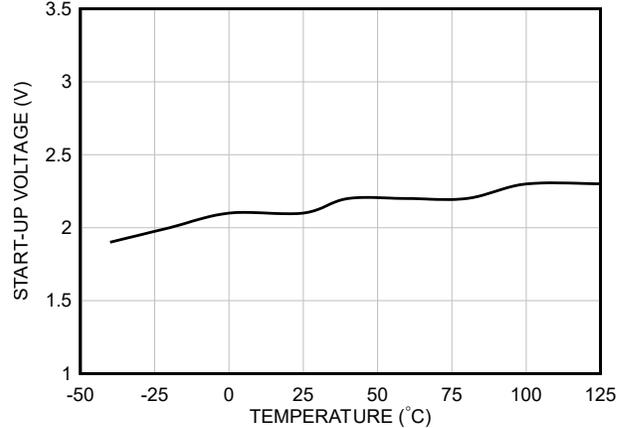
**Figure 6-7. Thermal Response in Still Air Without a Heat Sink (Legacy chip)**



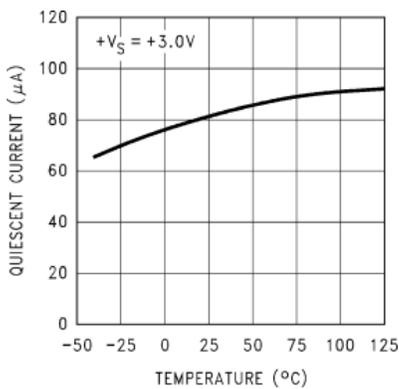
**Figure 6-8. Thermal Response in Still Air Without a Heat Sink (Both Legacy and New chip in the new test setup)**



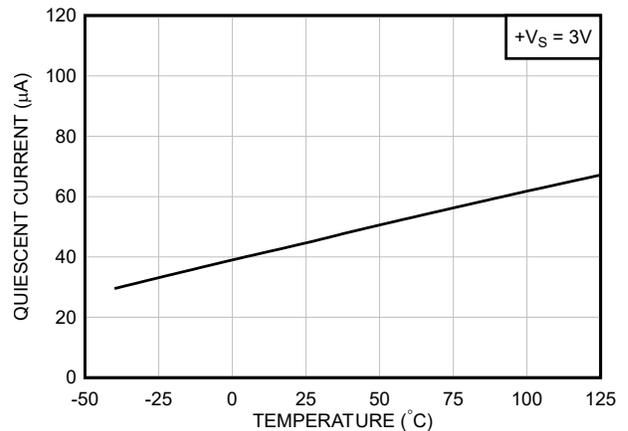
**Figure 6-9. Start-Up Voltage vs Temperature (Legacy chip)**



**Figure 6-10. Start-Up Voltage vs Temperature (New chip)**



**Figure 6-11. Quiescent Current vs Temperature (Legacy chip)**



**Figure 6-12. Quiescent Current vs Temperature (New chip)**

### 6.6 Typical Characteristics (continued)

To generate these curves, the device is mounted to a printed-circuit board as shown in [Figure 8-9](#) or [Figure 8-10](#).

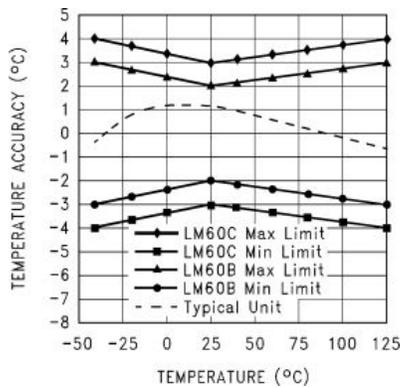


Figure 6-13. Accuracy vs Temperature (Legacy chip)

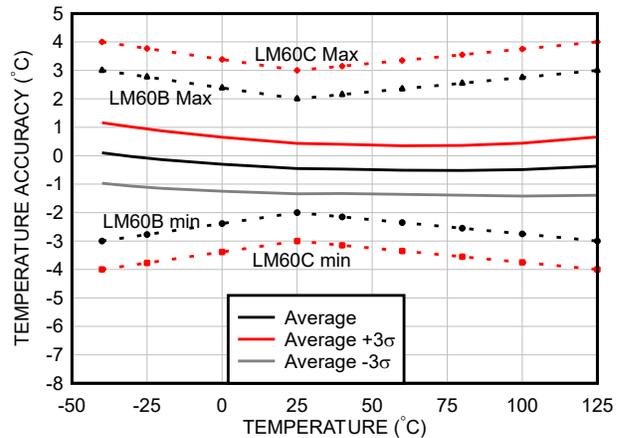


Figure 6-14. Accuracy vs Temperature (New chip)

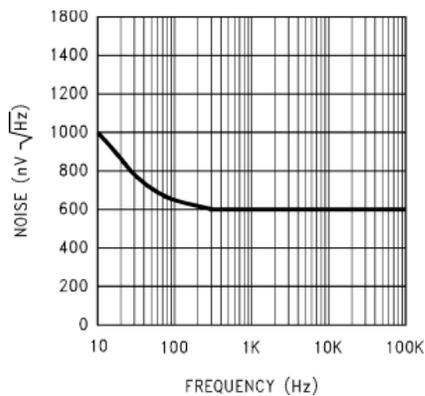


Figure 6-15. Noise Voltage (Legacy chip)

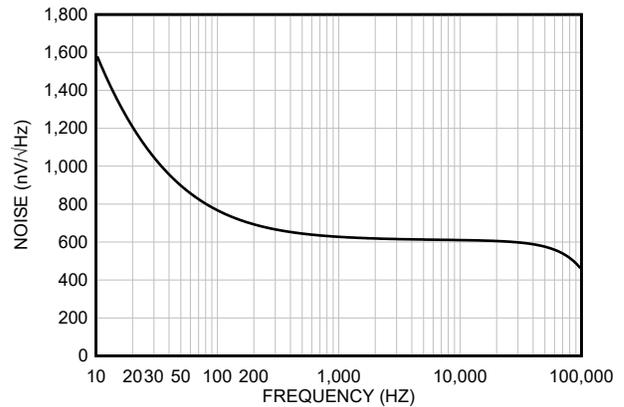


Figure 6-16. Noise Voltage (New chip)

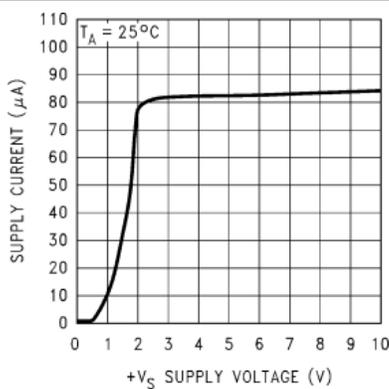


Figure 6-17. Supply Current vs Supply Voltage (Legacy chip)

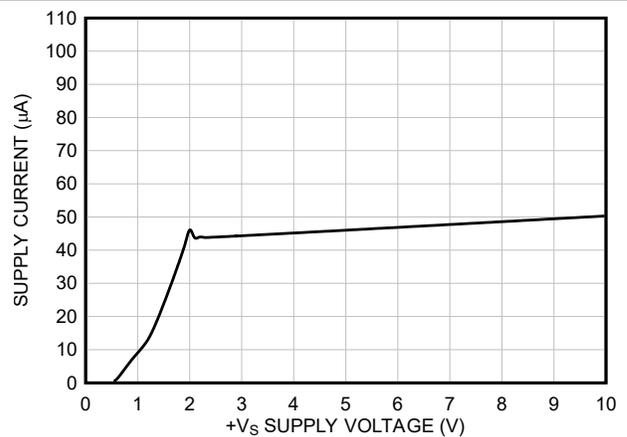
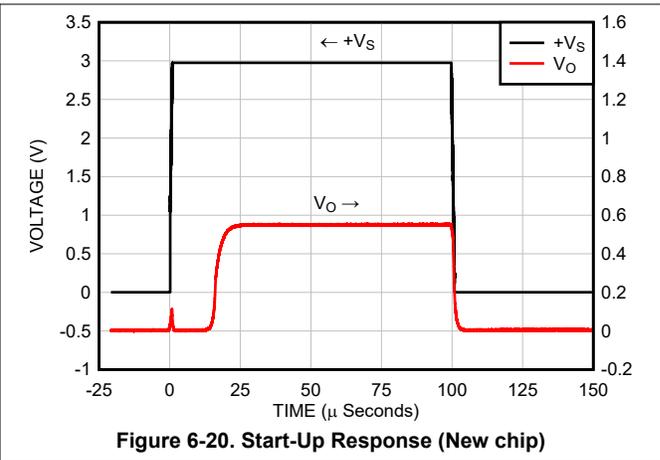
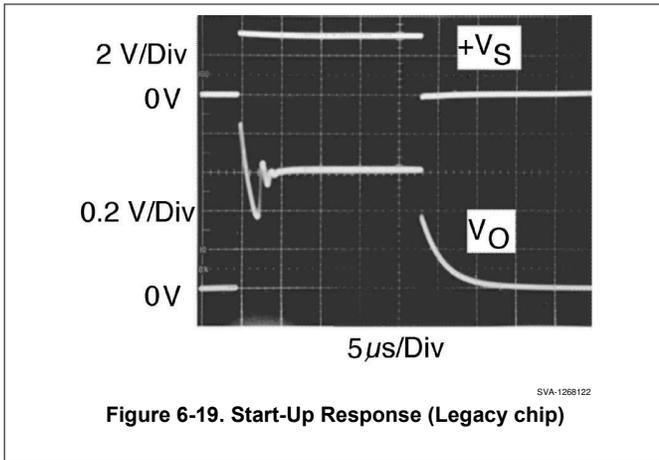


Figure 6-18. Supply Current vs Supply Voltage (New chip)

## 6.6 Typical Characteristics (continued)

To generate these curves, the device is mounted to a printed-circuit board as shown in [Figure 8-9](#) or [Figure 8-10](#).



## 7 Detailed Description

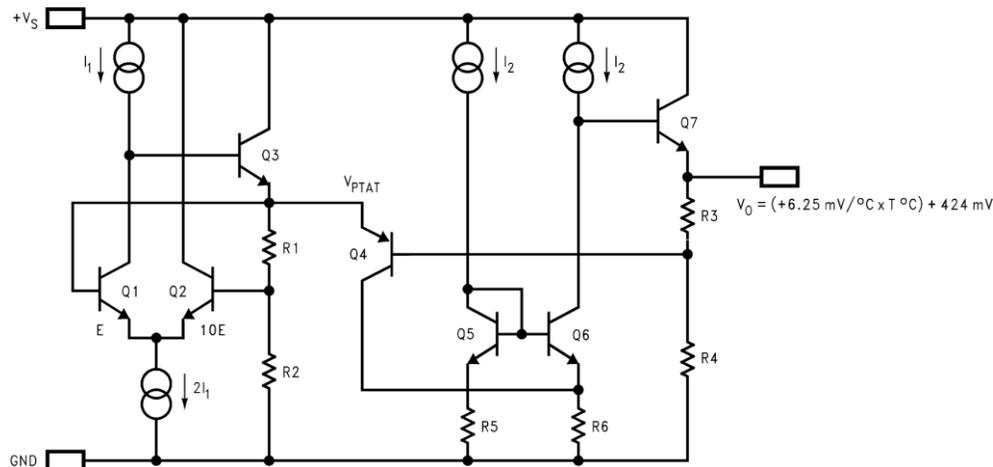
### 7.1 Overview

The LM60 device is a precision analog bipolar temperature sensor that can sense a  $-40^{\circ}\text{C}$  to  $+125^{\circ}\text{C}$  temperature range while operating from a single 2.7V supply. The output voltage of the LM60 is linearly proportional to Celsius (Centigrade) temperature ( $6.25\text{mV}/^{\circ}\text{C}$ ) and has a DC offset of 424mV. The offset allows reading negative temperatures with a single positive supply. The nominal output voltage of the device ranges from 174mV to 1205mV for a  $-40^{\circ}\text{C}$  to  $+125^{\circ}\text{C}$  temperature range. The device is calibrated to provide accuracies of  $\pm 2.0^{\circ}\text{C}$  at room temperature and  $\pm 3^{\circ}\text{C}$  over the full  $-25^{\circ}\text{C}$  to  $+125^{\circ}\text{C}$  (for Legacy chip) or  $-40^{\circ}\text{C}$  to  $+125^{\circ}\text{C}$  (for New chip) temperature range.

With a quiescent current of the device is less than  $110\mu\text{A}$  (for Legacy chip) and  $70\mu\text{A}$  (for New chip), self-heating is limited to a very low  $0.1^{\circ}\text{C}$  in still air in the SOT-23 package. Shutdown capability for the device is intrinsic because the inherent low power consumption allows the device to be powered directly from the output of many logic gates.

The output of the LM60 is a Class A base emitter follower, thus the LM60 can source quite a bit of current while sinking less than  $1\mu\text{A}$ . In any event load current must be minimized to limit the contribution to the total temperature error.

### 7.2 Functional Block Diagram



### 7.3 Feature Description

#### 7.3.1 LM60 Transfer Function

The LM60 follows a simple linear transfer function to achieve the accuracy as listed in [Section 6.5](#) as given:

$$V_O = (6.25\text{mV}/^{\circ}\text{C} \times T \text{ }^{\circ}\text{C}) + 424\text{mV} \quad (1)$$

where

- T is the temperature
- $V_O$  is the LM60 output voltage

### 7.4 Device Functional Modes

The only functional mode for this device is an analog output directly proportional to temperature.

## 8 Application and Implementation

### Note

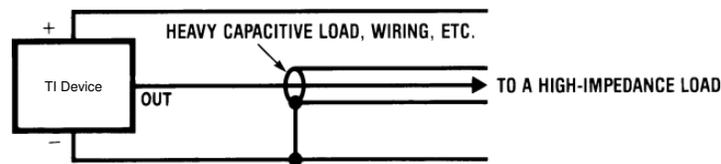
Information in the following applications sections is not part of the TI component specification, and TI does not warrant its accuracy or completeness. TI's customers are responsible for determining suitability of components for their purposes, as well as validating and testing their design implementation to confirm system functionality.

### 8.1 Application Information

The device has a low supply current and a wide supply range, therefore it can easily be driven by a battery.

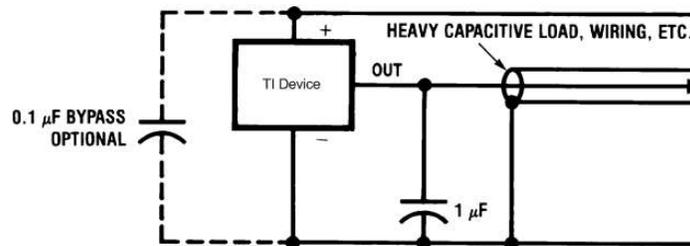
#### 8.1.1 Capacitive Loads

The device handles capacitive loading well. Without any special precautions, the device can drive any capacitive load as shown in Figure 8-1. Over the specified temperature range the device has a maximum output impedance of  $800\Omega$ . In an extremely noisy environment, adding some filtering to minimize noise pick-up can be required. TI recommends that  $0.1\mu\text{F}$  be added from  $+V_S$  to GND to bypass the power supply voltage, as shown in Figure 8-2. In a noisy environment, adding a capacitor from the output to ground can be required. A  $1\mu\text{F}$  output capacitor with the  $800\Omega$  output impedance forms a  $199\text{Hz}$ , low-pass filter. Because the thermal time constant of the device is much slower than the  $6.3\text{ms}$  time constant formed by the RC, the overall response time of the device is not be significantly affected. For much larger capacitors, this additional time lag increases the overall response time of the device.



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**Figure 8-1. No Decoupling Required for Capacitive Load**



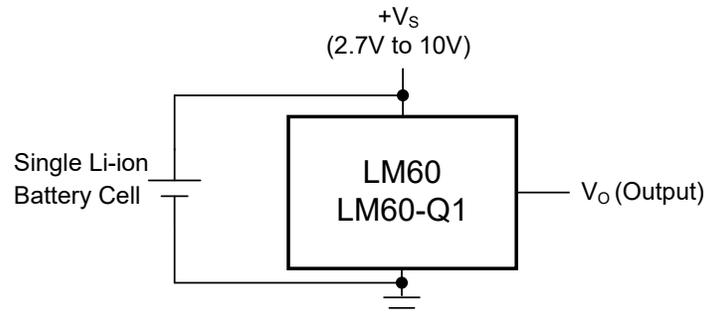
Copyright © 2017, Texas Instruments Incorporated

**Figure 8-2. Filter Added for Noisy Environment**

## 8.2 Typical Applications

### 8.2.1 Full-Range Centigrade Temperature Sensor

Because the LM60 is a simple temperature sensor that provides an analog output, design requirements related to the layout are also important. Refer to [Section 8.5](#) for details.



$$V_O = (6.25\text{mV}/^\circ\text{C} \times T^\circ\text{C}) + 424\text{mV}$$

**Figure 8-3. Full-Range Centigrade Temperature Sensor (–40°C to +125°C) Operating From a Single Li-Ion Battery Cell**

#### 8.2.1.1 Design Requirements

For this design example, use the design parameters listed in [Table 8-1](#).

**Table 8-1. Temperature and Typical V<sub>O</sub> Values of Figure 8-3**

TEMPERATURE (T)	TYPICAL V <sub>O</sub>
125°C	1205mV
100°C	1049mV
25°C	580mV
0°C	424mV
–25°C	268mV
–40°C	174mV

#### 8.2.1.2 Detailed Design Procedure

Selection of the LM60 is based on the output voltage transfer function being able to meet the needs of the rest of the system.

### 8.2.1.3 Application Curve

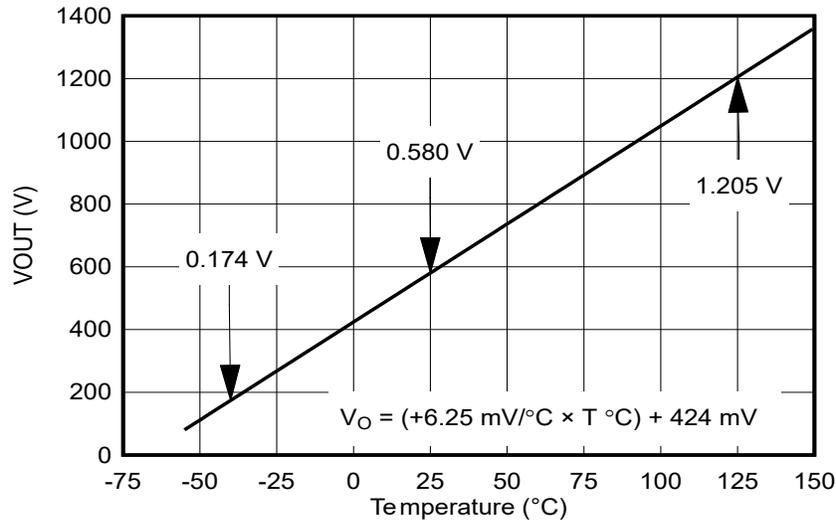
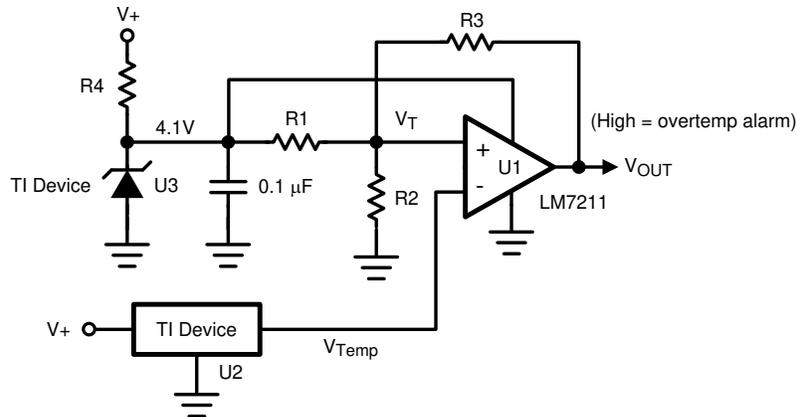


Figure 8-4. LM60 Output Transfer Function

### 8.2.2 Centigrade Thermostat Application



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Figure 8-5. Centigrade Thermostat

#### 8.2.2.1 Design Requirements

A simple thermostat can be created by using a reference (LM4040) and a comparator (LM7211 or LMC7211-N) as shown in Figure 8-5.

#### 8.2.2.2 Detailed Design Procedure

Use Equation 2 and Equation 3 to calculate the threshold values for T1 and T2.

$$V_{T1} = \frac{(4.1)R2}{R2 + R1 \parallel R3} \quad (2)$$

$$V_{T2} = \frac{(4.1)R2 \parallel R3}{R1 + R2 \parallel R3} \quad (3)$$

### 8.2.2.3 Application Curve

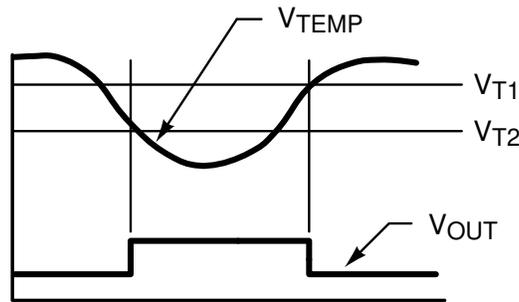
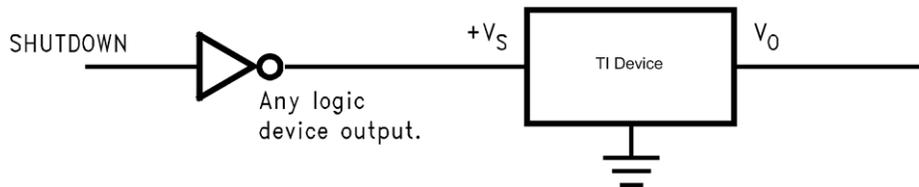


Figure 8-6. Thermostat Output Waveform

## 8.3 System Examples

### 8.3.1 Conserving Power Dissipation With Shutdown

The LM60 draws very little power, therefore the device can simply be shutdown by driving the LM60 supply pin with the output of a logic gate as shown in Figure 8-7.



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Figure 8-7. Conserving Power Dissipation With Shutdown

## 8.4 Power Supply Recommendations

In an extremely noisy environment, add some filtering to minimize noise pick-up. Adding 0.1µF from +V<sub>S</sub> to GND is recommended to bypass the power supply voltage, as shown in Figure 8-2. In a noisy environment, add a capacitor from the output to ground.

## 8.5 Layout

### 8.5.1 Layout Guidelines

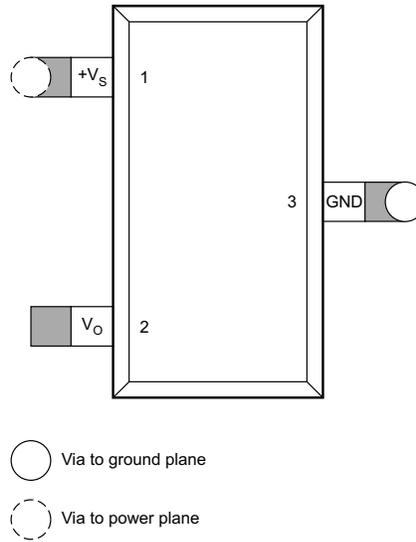
The LM60 can be applied easily in the same way as other integrated-circuit temperature sensors. The device can be glued or cemented to a surface. The temperature that the LM60 is sensing is within approximately +0.1°C of the surface temperature that the leads of the LM60 are attached to.

This presumes that the ambient air temperature is almost the same as the surface temperature. If the air temperature is much higher or lower than the surface temperature, the actual temperature of the device die is at an intermediate temperature between the surface temperature and the air temperature.

To provide good thermal conductivity, the backside of the device die is directly attached to the GND pin. The lands and traces to the device are part of the printed-circuit board, which is the object whose temperature is being measured. These printed-circuit board lands and traces do not cause the temperature of the device to deviate from the desired temperature.

Alternatively, the device can be mounted inside a sealed-end metal tube, and can then be dipped into a bath or screwed into a threaded hole in a tank. As with any IC, the device and accompanying wiring and circuits must be kept insulated and dry to avoid leakage and corrosion. Specifically when the device operates at cold temperatures where condensation can occur. Printed-circuit coatings and varnishes such as a conformal coating and epoxy paints or dips are often used to verify that moisture cannot corrode the device or connections.

### 8.5.2 Layout Example



1/2-inch square printed circuit board with 2-oz. copper foil or similar.

**Figure 8-8. PCB Layout**

### 8.5.3 Thermal Considerations

The thermal resistance junction to ambient ( $R_{\theta JA}$ ) is the parameter used to calculate the rise of a device junction temperature due to the device power dissipation. Use [Equation 4](#) to calculate the rise in the die temperature of the device.

$$T_J = T_A + R_{\theta JA} [(+V_S I_Q) + (+V_S - V_O) I_L] \quad (4)$$

where

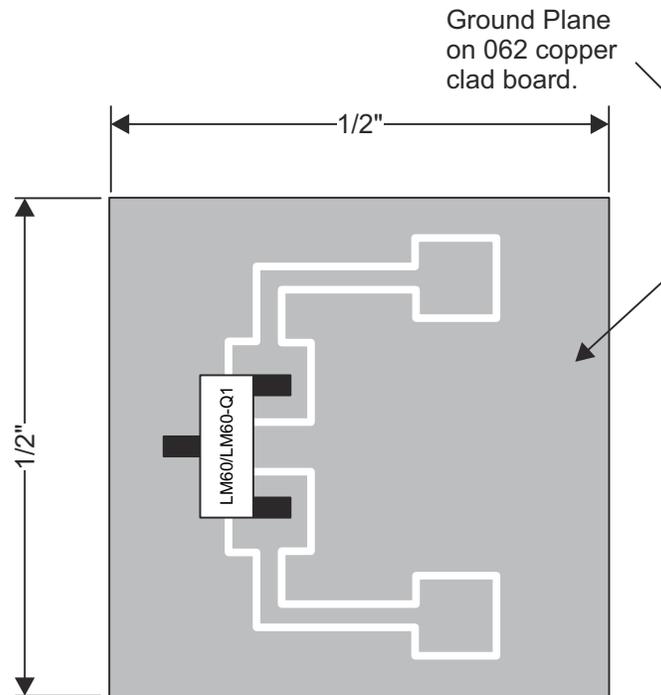
- $I_Q$  is the quiescent current
- $I_L$  is the load current on the output

[Table 8-2](#) summarizes the rise in die temperature of the LM60 without any loading, and the thermal resistance for different conditions. The values in [Table 8-2](#) were actually measured where as the values shown in [Section 6.4](#) where calculated using modeling methods as described in the [Semiconductor and IC Package Thermal Metrics \(SPRA953\)](#) application report.

**Table 8-2. Temperature Rise of LM60 Due to Self-Heating and Thermal Resistance ( $R_{\theta JA}$ )**

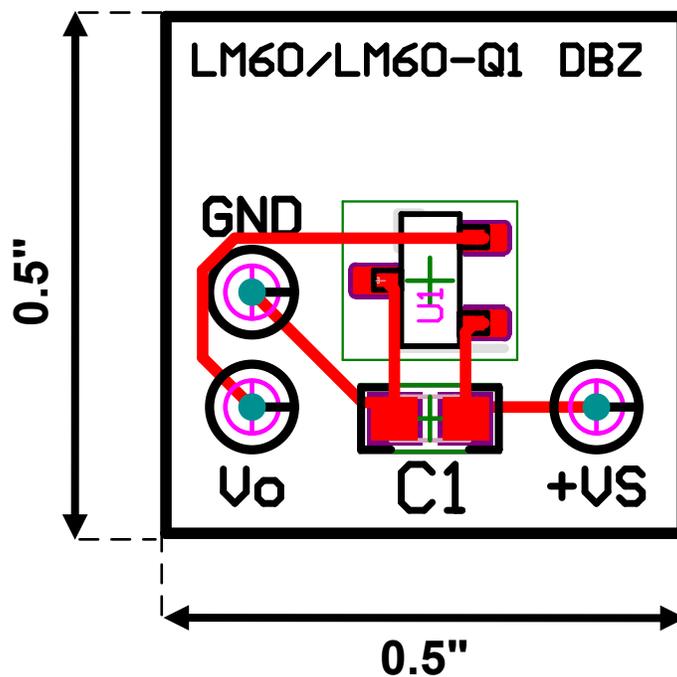
	SOT-23 <sup>(1)</sup> NO HEAT SINK		SOT-23 <sup>(2)</sup> SMALL HEAT FIN		TO-92 <sup>(1)</sup> NO HEAT FIN		TO-92 <sup>(3)</sup> SMALL HEAT FIN	
	$R_{\theta JA}$	$T_J - T_A$	$R_{\theta JA}$	$T_J - T_A$	$R_{\theta JA}$	$T_J - T_A$	$R_{\theta JA}$	$T_J - T_A$
	(°C/W)	(°C)	(°C/W)	(°C)	(°C/W)	(°C)	(°C/W)	(°C)
Still air Legacy chip	450	0.17	260	0.1	180	0.07	140	0.05
Moving air Legacy chip	—	—	180	0.07	90	0.034	70	0.026

- (1) Part soldered to 30 gauge wire.
- (2) Heat sink used is 1/2-in square printed-circuit board with 2-oz. foil with part attached as shown in [Figure 8-9](#).
- (3) Part glued or leads soldered to 1-in square of 1/16-in printed-circuit board with 2-oz. foil or similar.



1/2-in Square Printed-Circuit Board with 2oz. Copper Foil or Similar.

**Figure 8-9. Printed-Circuit Board Used for Heat Sink to Generate Thermal Response Curves (Legacy chip)**



1/2in Square Printed-Circuit Board with FR-4 material.

**Figure 8-10. Printed-Circuit Board Used to Generate Thermal Response Curves (New Test Setup for Both New Chip and Legacy Chip)**

## 9 Device and Documentation Support

### 9.1 Documentation Support

#### 9.1.1 Related Documentation

For related documentation see the following:

- Texas Instruments, [LM50 and LM50-Q1 SOT-23 Single-Supply Centigrade Temperature Sensor](#), data sheet
- Texas Instruments, [TMP23x Low-Power, High-Accuracy Analog Output Temperature Sensors](#), data sheet
- Texas Instruments, [LM60 Evaluation Module](#), EVM user's guide
- Texas Instruments, [LM60-Q1 Functional Safety FIT Rate and FMD](#), Functional safety information.

### 9.2 Receiving Notification of Documentation Updates

To receive notification of documentation updates, navigate to the device product folder on [ti.com](#). Click on *Notifications* to register and receive a weekly digest of any product information that has changed. For change details, review the revision history included in any revised document.

### 9.3 Support Resources

[TI E2E™ support forums](#) are an engineer's go-to source for fast, verified answers and design help — straight from the experts. Search existing answers or ask your own question to get the quick design help you need.

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### 9.5 Electrostatic Discharge Caution



This integrated circuit can be damaged by ESD. Texas Instruments recommends that all integrated circuits be handled with appropriate precautions. Failure to observe proper handling and installation procedures can cause damage.

ESD damage can range from subtle performance degradation to complete device failure. Precision integrated circuits may be more susceptible to damage because very small parametric changes could cause the device not to meet its published specifications.

### 9.6 Glossary

[TI Glossary](#) This glossary lists and explains terms, acronyms, and definitions.

## 10 Revision History

Changes from Revision F (August 2017) to Revision G (February 2025)	Page
• Updated the numbering format for tables, figures, and cross-references throughout the document .....	1
• Updated the <i>Device Comparison</i> section with existing OPNs and adding <i>Device Nomenclature</i> table.....	3
• Changed Machine model (MM) Electrostatic discharge to Charged-device model (CDM).....	4
• Changed minimum specified temperature for LM60B from -25°C to -40°C in the New chip.....	4
• Changed DBZ and LP packages Thermal Information section. in the New chip.....	4
• Added “operating current” and “Change of quiescent current” for the New chip.....	5
• Added graphs for new chip, reordered and corrected the graphs for legacy chip.....	6
• Added corrections to the <i>Thermal Resistance Junction to Air (Legacy chip)</i> graph.....	6
• Added <i>Thermal Response in Stirred Oil Bath With Heat Sink (0.5 inches × 0.5 inches PCB board)</i> graph for both Legacy and New chips.....	6
• Added <i>Thermal Response in Still Air Without a Heat Sink (Both Legacy and New chip together in a new test setup)</i> graph for both Legacy and New chips.....	6

- Added the *Start-Up Voltage vs Temperature*, *Quiescent Current vs Temperature*, *Accuracy vs Temperature*, *Noise Voltage*, *Supply Current vs Supply Voltage* and *Start-Up Response* graphs for New chip.....6
- 

#### **Changes from Revision E (September 2015) to Revision F (August 2017) Page**

- Moved the automotive device to a standalone data sheet (SNIS197).....1
  - Added table note for the LM60B.....3
- 

#### **Changes from Revision D (November 2012) to Revision E (November 2014) Page**

- Added *Pin Configuration and Functions* section, *ESD Ratings* table, *Feature Description* section, *Device Functional Modes*, *Application and Implementation* section, *Power Supply Recommendations* section, *Layout* section, *Device and Documentation Support* section, and *Mechanical, Packaging, and Orderable Information* section ..... 1
- 

## **11 Mechanical, Packaging, and Orderable Information**

The following pages include mechanical, packaging, and orderable information. This information is the most current data available for the designated devices. This data is subject to change without notice and revision of this document. For browser-based versions of this data sheet, refer to the left-hand navigation.

**PACKAGING INFORMATION**

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead finish/ Ball material (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
LM60BIM3	NRND	SOT-23	DBZ	3	1000	Non-RoHS & Green	Call TI	Level-1-260C-UNLIM	-25 to 125	T6B	
LM60BIM3/NOPB	OBSOLETE	SOT-23	DBZ	3		TBD	Call TI	Call TI	-25 to 125	T6B	
LM60BIM3X	NRND	SOT-23	DBZ	3	3000	Non-RoHS & Green	Call TI	Level-1-260C-UNLIM	-25 to 125	T6B	
LM60BIM3X/NOPB	ACTIVE	SOT-23	DBZ	3	3000	RoHS & Green	SN	Level-1-260C-UNLIM	-25 to 125	T6B	Samples
LM60BIZ/LFT3	ACTIVE	TO-92	LP	3	2000	RoHS & Green	SN	N / A for Pkg Type		LM60 BIZ	Samples
LM60BIZ/NOPB	ACTIVE	TO-92	LP	3	1800	RoHS & Green	Call TI	N / A for Pkg Type	-25 to 125	LM60 BIZ	Samples
LM60CIM3	NRND	SOT-23	DBZ	3	1000	Non-RoHS & Green	Call TI	Level-1-260C-UNLIM	-40 to 125	T6C	
LM60CIM3/NOPB	OBSOLETE	SOT-23	DBZ	3		TBD	Call TI	Call TI	-40 to 125	T6C	
LM60CIM3X	NRND	SOT-23	DBZ	3	3000	Non-RoHS & Green	Call TI	Level-1-260C-UNLIM	-40 to 125	T6C	
LM60CIM3X/NOPB	ACTIVE	SOT-23	DBZ	3	3000	RoHS & Green	SN	Level-1-260C-UNLIM	-40 to 125	T6C	Samples
LM60CIZ/NOPB	ACTIVE	TO-92	LP	3	1800	RoHS & Green	Call TI	N / A for Pkg Type	-40 to 125	LM60 CIZ	Samples

(1) The marketing status values are defined as follows:

**ACTIVE:** Product device recommended for new designs.

**LIFEBUY:** TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

**NRND:** Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

**PREVIEW:** Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

(2) **RoHS:** TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

**RoHS Exempt:** TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

**Green:** TI defines "Green" to mean the content of Chlorine (Cl) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

- (3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.
- (4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.
- (5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.
- (6) Lead finish/Ball material - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

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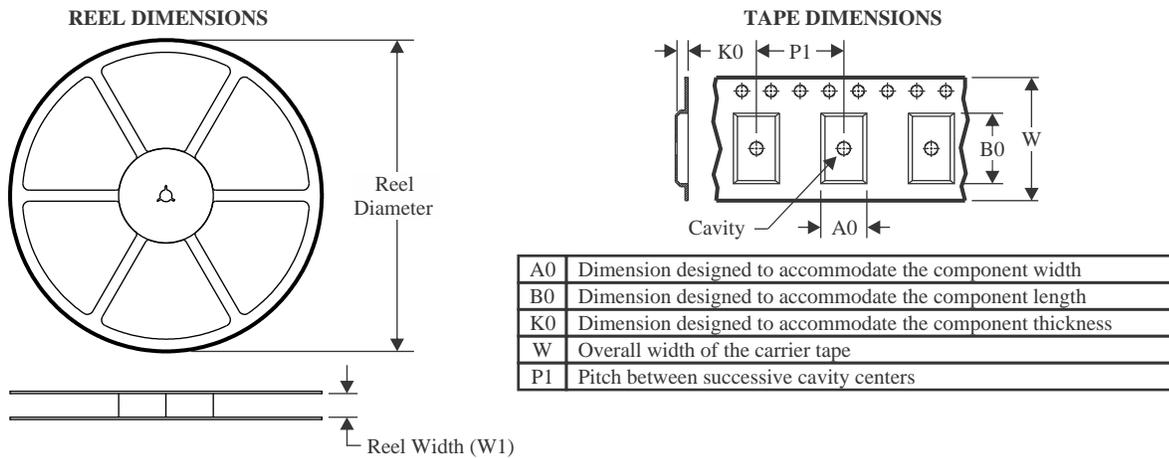
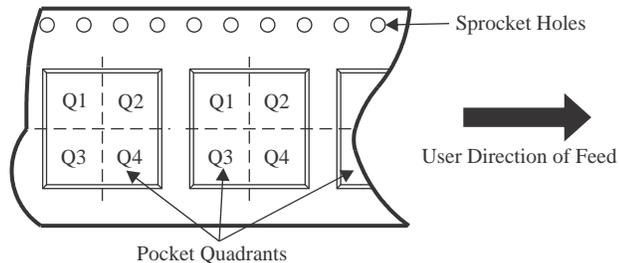
In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

**OTHER QUALIFIED VERSIONS OF LM60 :**

- Automotive : [LM60-Q1](#)

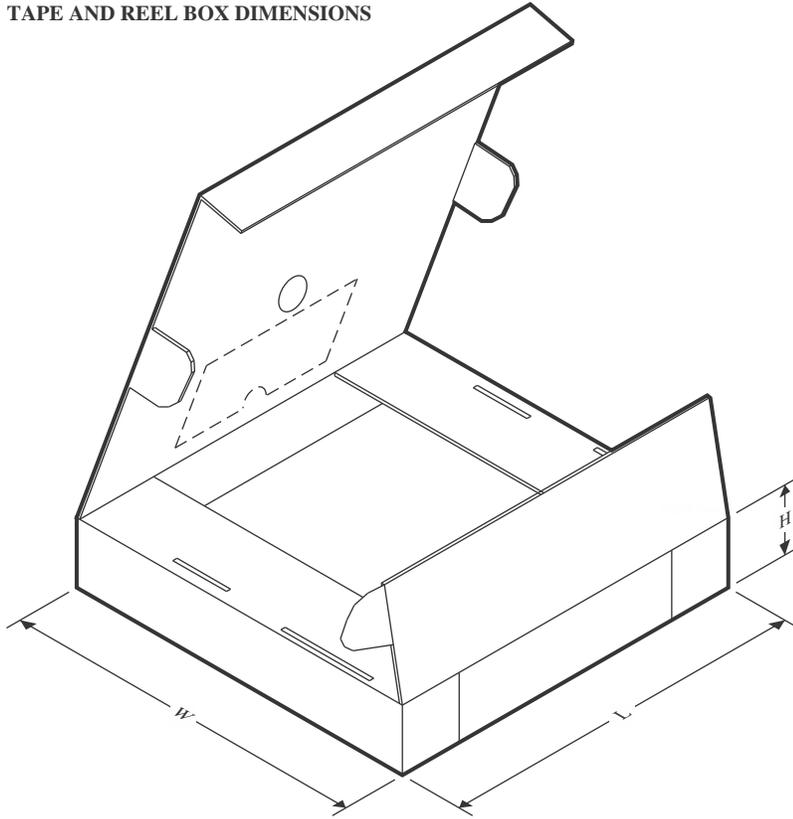
NOTE: Qualified Version Definitions:

- Automotive - Q100 devices qualified for high-reliability automotive applications targeting zero defects

**TAPE AND REEL INFORMATION**

**QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE**


\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
LM60BIM3	SOT-23	DBZ	3	1000	178.0	8.4	3.3	2.9	1.22	4.0	8.0	Q3
LM60BIM3X	SOT-23	DBZ	3	3000	178.0	8.4	3.3	2.9	1.22	4.0	8.0	Q3
LM60BIM3X/NOPB	SOT-23	DBZ	3	3000	178.0	8.4	3.3	2.9	1.22	4.0	8.0	Q3
LM60CIM3	SOT-23	DBZ	3	1000	178.0	8.4	3.3	2.9	1.22	4.0	8.0	Q3
LM60CIM3X	SOT-23	DBZ	3	3000	178.0	8.4	3.3	2.9	1.22	4.0	8.0	Q3
LM60CIM3X/NOPB	SOT-23	DBZ	3	3000	178.0	8.4	3.3	2.9	1.22	4.0	8.0	Q3

**TAPE AND REEL BOX DIMENSIONS**


\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
LM60BIM3	SOT-23	DBZ	3	1000	208.0	191.0	35.0
LM60BIM3X	SOT-23	DBZ	3	3000	208.0	191.0	35.0
LM60BIM3X/NOPB	SOT-23	DBZ	3	3000	208.0	191.0	35.0
LM60CIM3	SOT-23	DBZ	3	1000	208.0	191.0	35.0
LM60CIM3X	SOT-23	DBZ	3	3000	208.0	191.0	35.0
LM60CIM3X/NOPB	SOT-23	DBZ	3	3000	208.0	191.0	35.0

## GENERIC PACKAGE VIEW

LP 3

TO-92 - 5.34 mm max height

TRANSISTOR OUTLINE



Images above are just a representation of the package family, actual package may vary.  
Refer to the product data sheet for package details.

4040001-2/F

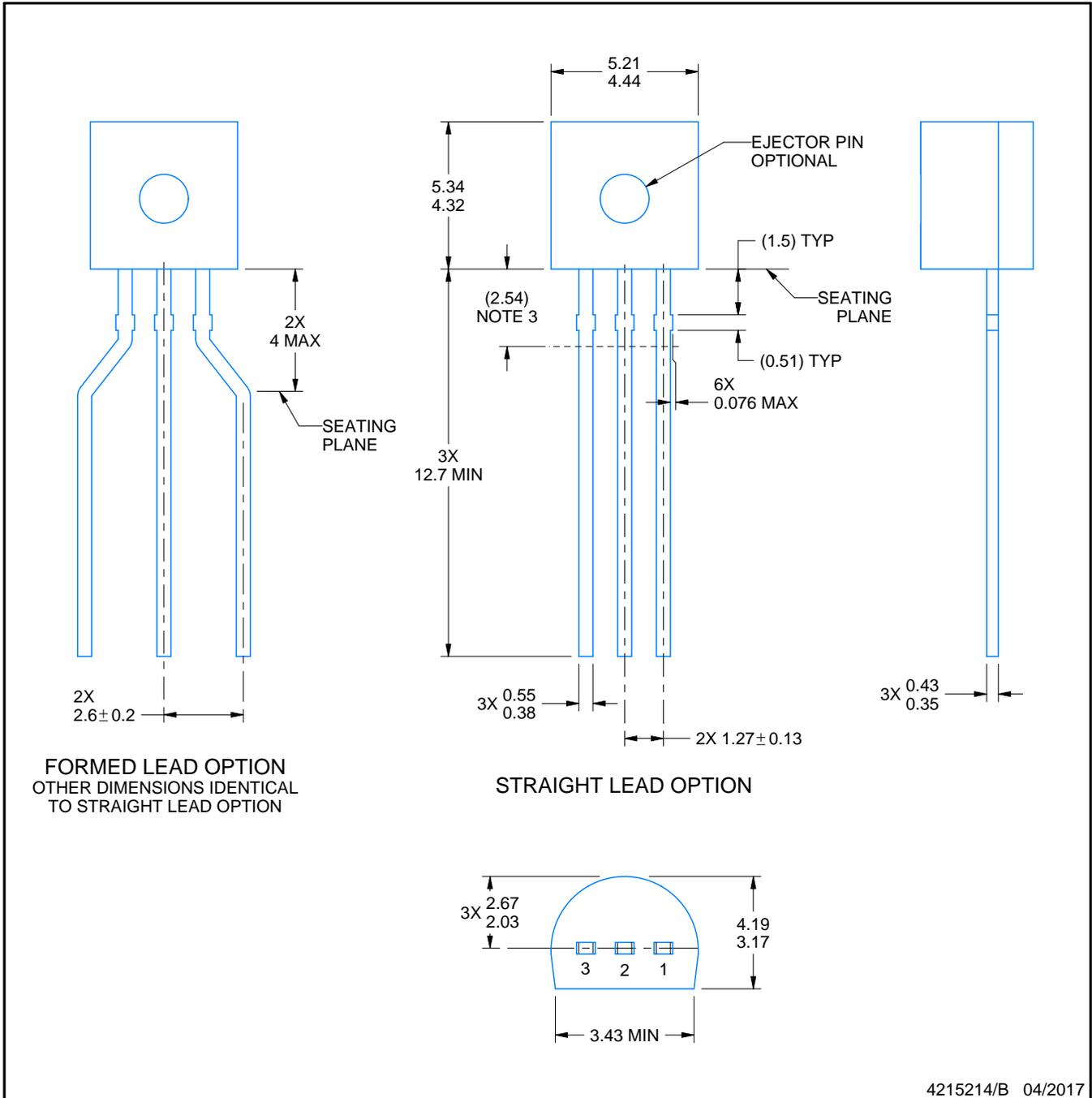
LP0003A



# PACKAGE OUTLINE

TO-92 - 5.34 mm max height

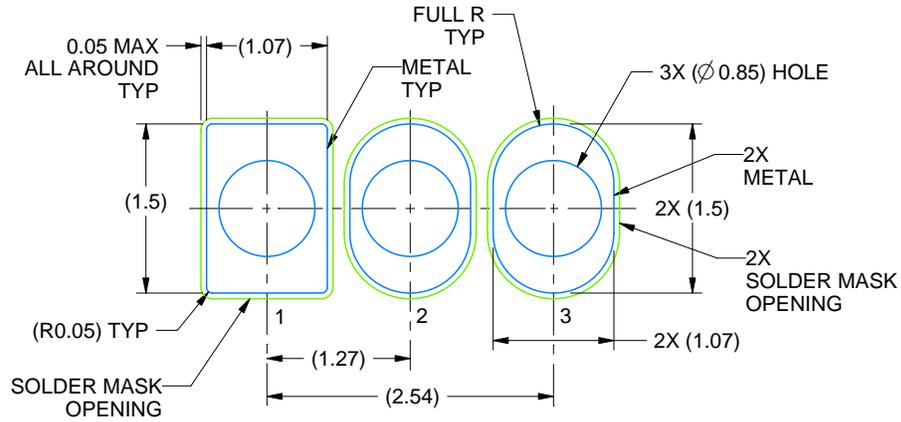
TO-92



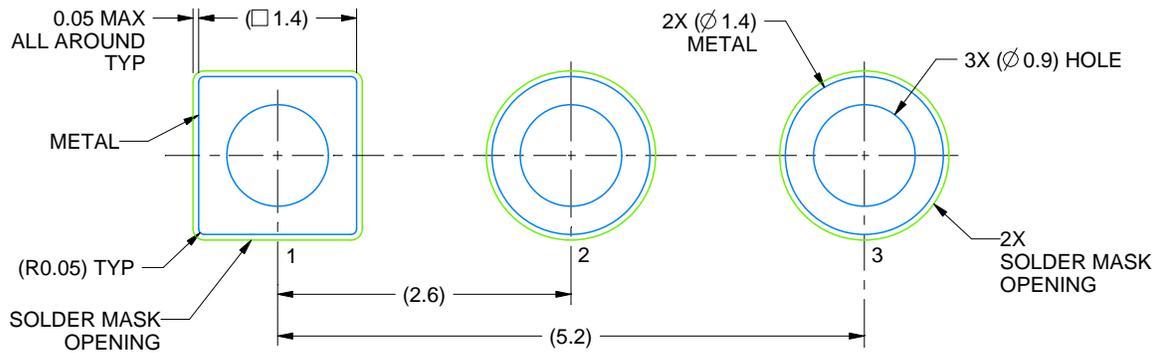
4215214/B 04/2017

NOTES:

1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. Lead dimensions are not controlled within this area.
4. Reference JEDEC TO-226, variation AA.
5. Shipping method:
  - a. Straight lead option available in bulk pack only.
  - b. Formed lead option available in tape and reel or ammo pack.
  - c. Specific products can be offered in limited combinations of shipping medium and lead options.
  - d. Consult product folder for more information on available options.



LAND PATTERN EXAMPLE  
STRAIGHT LEAD OPTION  
NON-SOLDER MASK DEFINED  
SCALE:15X



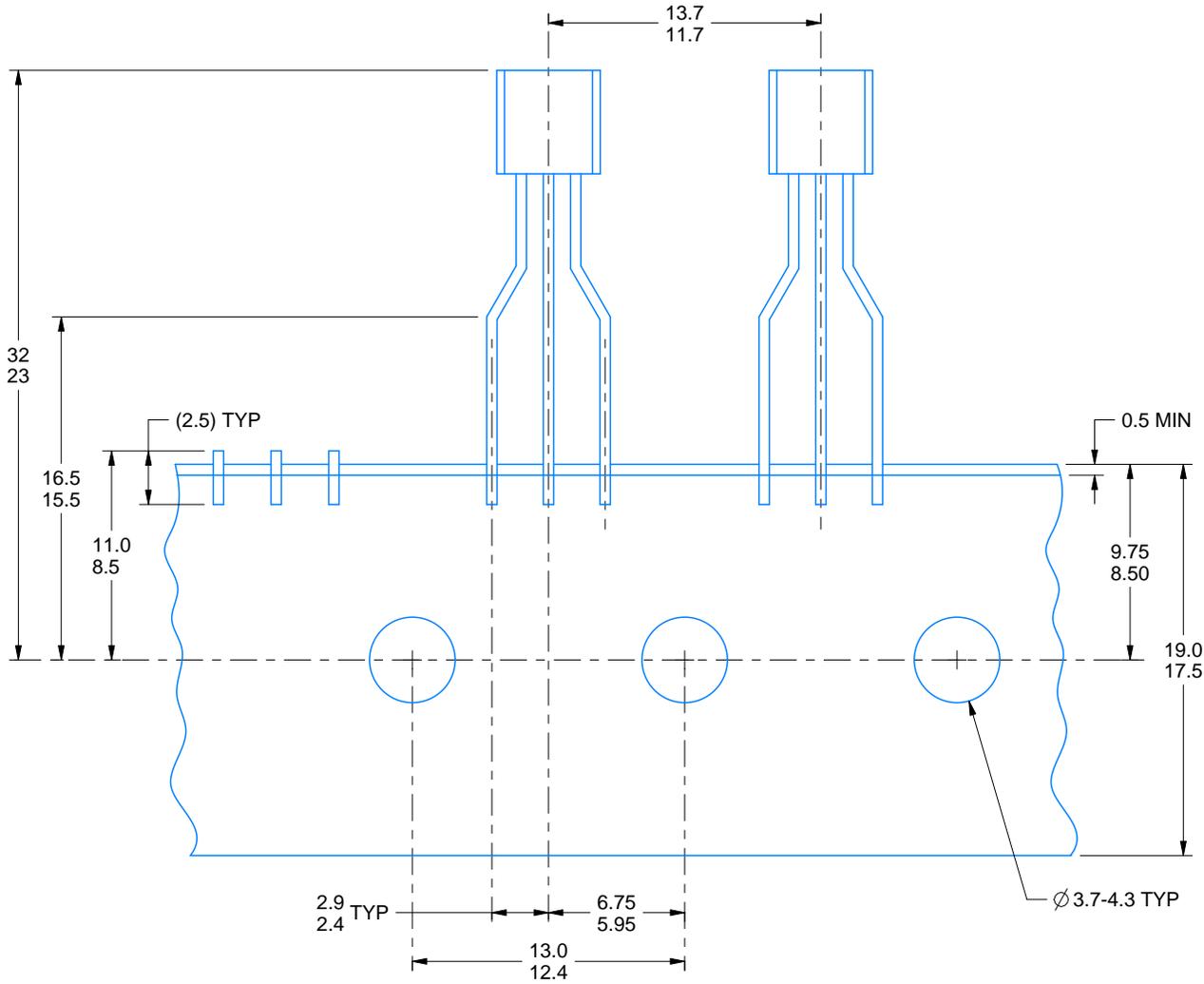
LAND PATTERN EXAMPLE  
FORMED LEAD OPTION  
NON-SOLDER MASK DEFINED  
SCALE:15X

**TAPE SPECIFICATIONS**

**LP0003A**

**TO-92 - 5.34 mm max height**

TO-92



FOR FORMED LEAD OPTION PACKAGE

4215214/B 04/2017

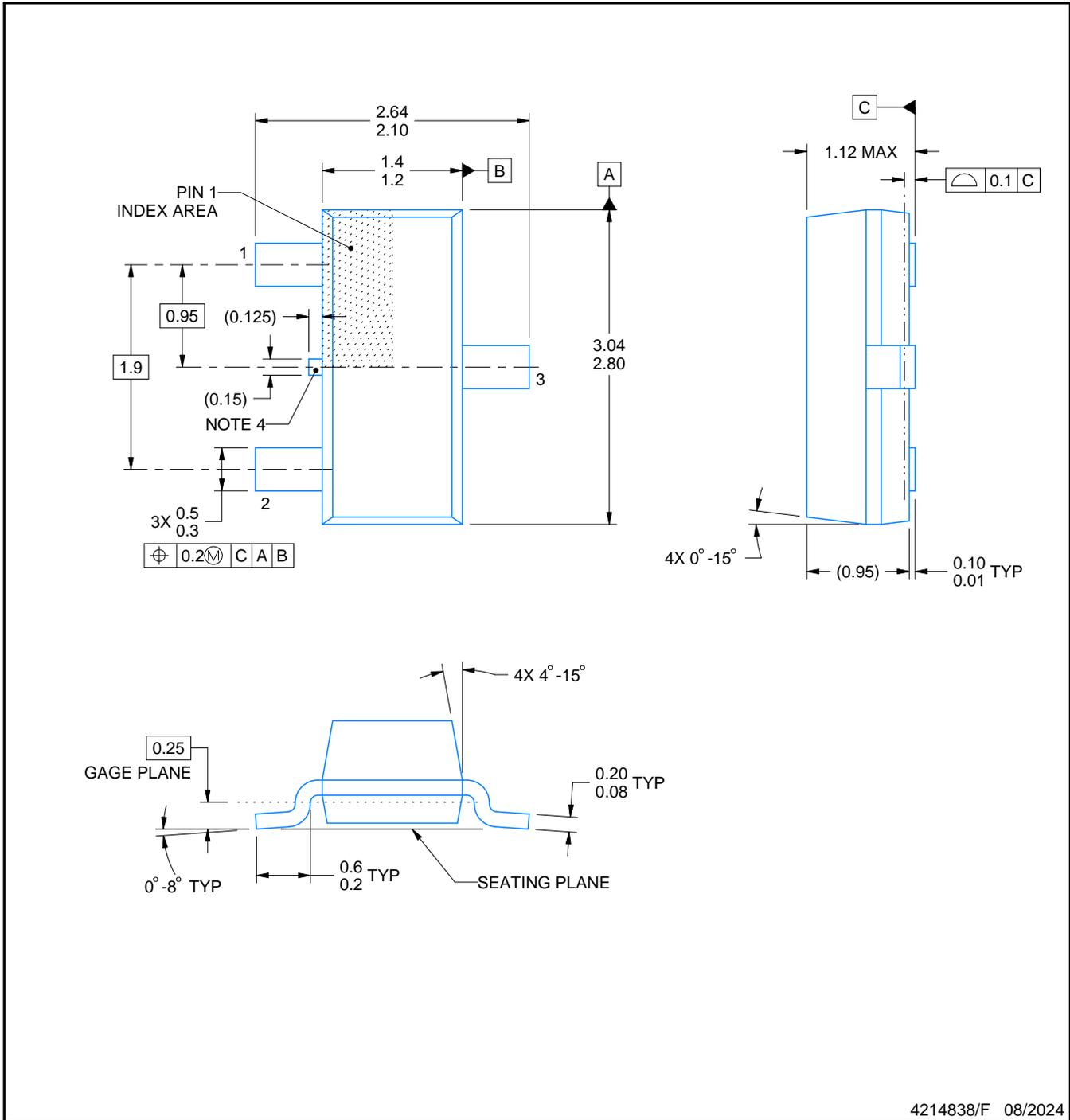
# DBZ0003A



# PACKAGE OUTLINE

## SOT-23 - 1.12 mm max height

SMALL OUTLINE TRANSISTOR



4214838/F 08/2024

### NOTES:

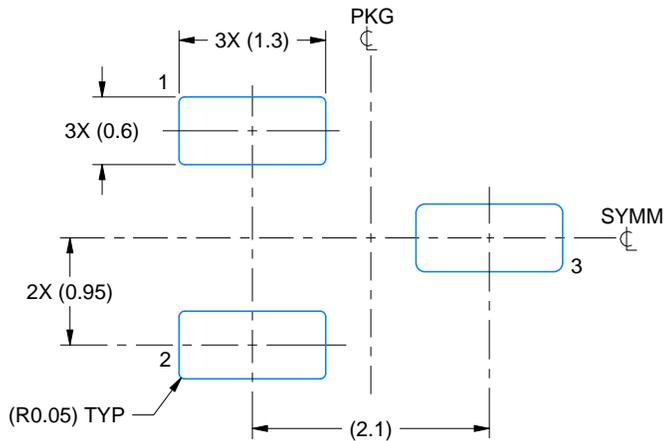
1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. Reference JEDEC registration TO-236, except minimum foot length.
4. Support pin may differ or may not be present.
5. Body dimensions do not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.25mm per side

# EXAMPLE BOARD LAYOUT

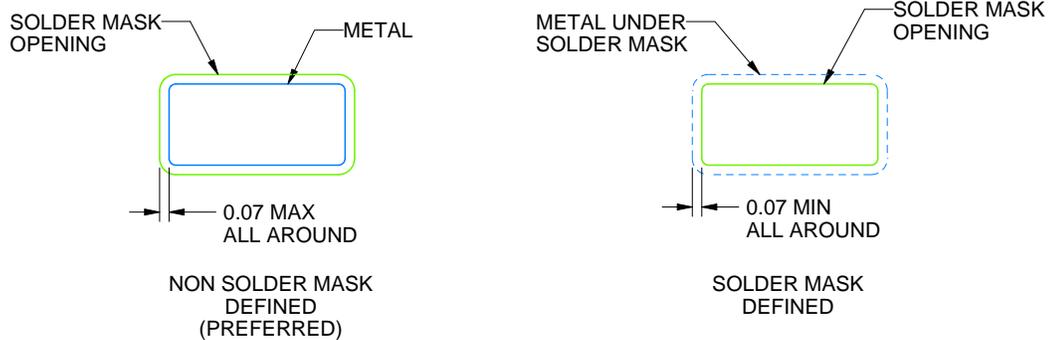
DBZ0003A

SOT-23 - 1.12 mm max height

SMALL OUTLINE TRANSISTOR



LAND PATTERN EXAMPLE  
SCALE:15X



SOLDER MASK DETAILS

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NOTES: (continued)

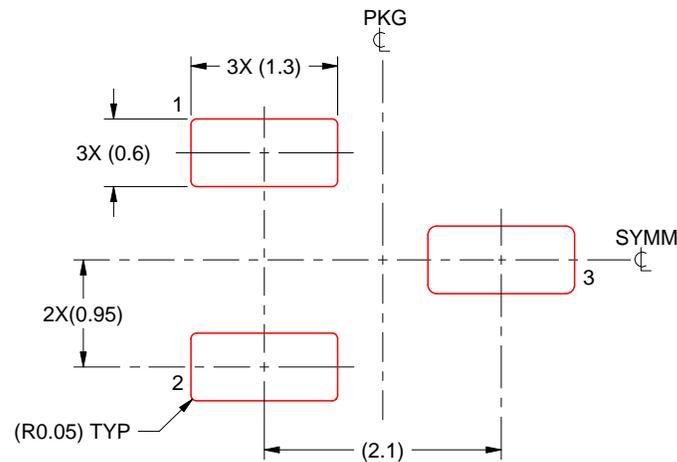
5. Publication IPC-7351 may have alternate designs.
6. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

# EXAMPLE STENCIL DESIGN

DBZ0003A

SOT-23 - 1.12 mm max height

SMALL OUTLINE TRANSISTOR



SOLDER PASTE EXAMPLE  
BASED ON 0.125 THICK STENCIL  
SCALE:15X

4214838/F 08/2024

NOTES: (continued)

7. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
8. Board assembly site may have different recommendations for stencil design.

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